SN74AUP1G17-EP
LOW-POWER SINGLE SCHMITT-TRIGGER BUFFER

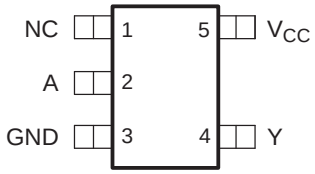
SCES684 – JANUARY 2007

FEATURES

- **Controlled Baseline**
  - **One Assembly/Test Site, One Fabrication Site**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree** (1)
- **Available in the Texas Instruments NanoStar™ and NanoFree™ Packages**
- **Low Static-Power Consumption (I_{CC} = 0.9 μA Max)**
- **Low Dynamic-Power Consumption (C_{pd} = 4.4 pF Typ at 3.3 V)**
- **Low Input Capacitance (C_I = 1.5 pF)**
- **Low Noise – Overshoot and Undershoot <10% of V_{CC}**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Includes Schmitt-Trigger Inputs**
- **Wide Operating V_{CC} Range of 0.8 V to 3.6 V**
- **Optimized for 3.3-V Operation**
- **3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation**
- **t_{pd} = 5.1 ns Max at 3.3 V**
- **Suitable for Point-to-Point Applications**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Performance Tested Per JESD 22**
  - **2000-V Human-Body Model (A114-B, Class II)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**
- **ESD Protection Exceeds 5000 V With Human-Body Model**

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

DCK PACKAGE
(TOP VIEW)



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire V_{CC} range of 0.8 V to 3.6 V, resulting in an increased battery life. This product also maintains excellent signal integrity (see Figures 1 and 2).

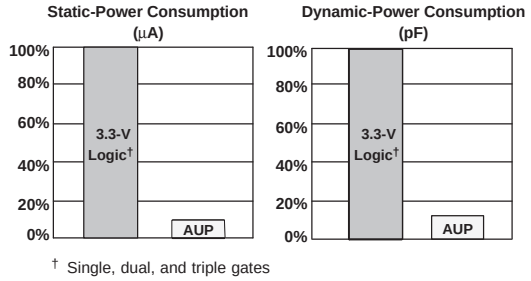


Figure 1. AUP - The Lowest-Power Family

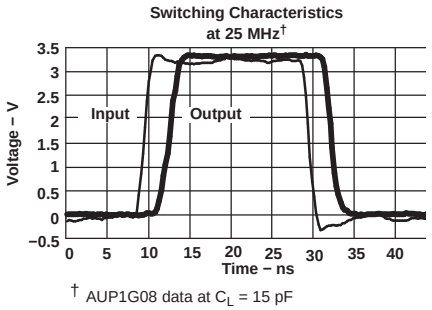


Figure 2. Excellent Signal Integrity

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

This device functions as an independent gate with Schmitt-trigger inputs, which allows for slow input transition and better switching noise immunity at the input.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

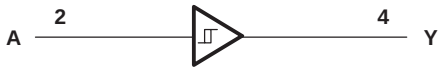
T_A	PACKAGE(1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING(2)
–55°C to 125°C	SOT (SC-70) – DCK	Reel of 3000	SN74AUP1G17MDCKREP	BZU

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
(2) DCK: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site. The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

FUNCTION TABLE

INPUTS A	OUTPUT Y
H	H
L	L

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	4.6	V
V_I	Input voltage range(2)		–0.5	4.6	V
V_O	Voltage range applied to any output in the high-impedance or power-off state(2)		–0.5	4.6	V
V_O	Output voltage range in the high or low state(2)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–50	mA
I_{OK}	Output clamp current	V_O < 0		–50	mA
I_O	Continuous output current			±20	mA
	Continuous current through V_{CC} or GND			±50	mA
θ_{JA}	Package thermal impedance(3)	DCK package		227	°C/W
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		0.8	3.6	V
V_I	Input voltage		0	3.6	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 0.8 V		–20	µA
		V_{CC} = 1.1 V		–1.1	mA
		V_{CC} = 1.4 V		–1.7	
		V_{CC} = 1.65 V		–1.9	
		V_{CC} = 2.3 V		–3.1	
		V_{CC} = 3 V		–4	
I_{OL}	Low-level output current	V_{CC} = 0.8 V		20	µA
		V_{CC} = 1.1 V		1.1	mA
		V_{CC} = 1.4 V		1.7	
		V_{CC} = 1.65 V		1.9	
		V_{CC} = 2.3 V		3.1	
		V_{CC} = 3 V		4	
T_A	Operating free-air temperature		–55	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = –55°C to 125°C			UNIT
				MIN	TYP	MAX	
V_{T+} Positive-going input threshold voltage			0.8 V	0.3		0.6	V
			1.1 V	0.53		0.9	
			1.4 V	0.74		1.11	
			1.65 V	0.91		1.29	
			2.3 V	1.37		1.77	
			3 V	1.88		2.29	
$V_{T–}$ Negative-going input threshold voltage			0.8 V	0.1		0.6	V
			1.1 V	0.26		0.65	
			1.4 V	0.39		0.75	
			1.65 V	0.47		0.84	
			2.3 V	0.69		1.04	
			3 V	0.88		1.24	
ΔV_T Hysteresis ($V_{T+} – V_{T–}$)			0.8 V	0.07		0.5	V
			1.1 V	0.08		0.46	
			1.4 V	0.18		0.56	
			1.65 V	0.27		0.66	
			2.3 V	0.53		0.92	
			3 V	0.79		1.31	
V_{OH}		I_{OH} = –20 µA	0.8 V to 3.6 V	V_{CC} – 0.2			V
		I_{OH} = –1.1 mA	1.1 V	0.7 × V_{CC}			
		I_{OH} = –1.7 mA	1.4 V	1.03			
		I_{OH} = –1.9 mA	1.65 V	1.3			
		I_{OH} = –2.3 mA	2.3 V	1.97			
		I_{OH} = –3.1 mA		1.85			
		I_{OH} = –2.7 mA	3 V	2.67			
		I_{OH} = –4 mA		2.55			
V_{OL}		I_{OL} = 20 µA	0.8 V to 3.6 V			0.1	V
		I_{OL} = 1.1 mA	1.1 V			0.3 × V_{CC}	
		I_{OL} = 1.7 mA	1.4 V			0.37	
		I_{OL} = 1.9 mA	1.65 V			0.35	
		I_{OL} = 2.3 mA	2.3 V			0.33	
		I_{OL} = 3.1 mA				0.45	
		I_{OL} = 2.7 mA	3 V			0.33	
		I_{OL} = 4 mA				0.475	
I_I	All inputs	V_I = GND to 3.6 V	0 V to 3.6 V			0.5	µA
I_{off}		V_I or V_O = 0 V to 3.6 V	0 V			5.0	µA
ΔI_{off}		V_I or V_O = 0 V to 3.6 V	0 V to 0.2 V			5.0	µA
I_{CC}		V_I = GND or (V_{CC} to 3.6 V), I_O = 0	0.8 V to 3.6 V			0.9	µA
ΔI_{CC}		V_I = V_{CC} – 0.6 V, I_O = 0	3.3 V			50	µA
C_i		V_I = V_{CC} or GND	0 V		1.5		pF
			3.6 V		1.5		
C_o		V_O = GND	0 V		2.5		pF

Switching Characteristics

over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 3 and Figure 4)

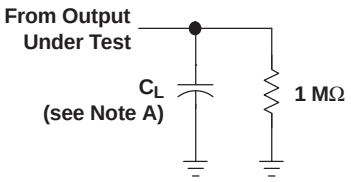
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = –55°C to 125°C		UNIT
				MIN	MAX	
t_{pd}	A	Y	1.2 V ± 0.1 V	7.5	28	ns
			1.5 V ± 0.1 V	5.6	20	
			1.8 V ± 0.15 V	4.8	17	
			2.5 V ± 0.2 V	4	13	
			3.3 V ± 0.3 V	3.6	11	

Operating Characteristics

T_A = 25°C

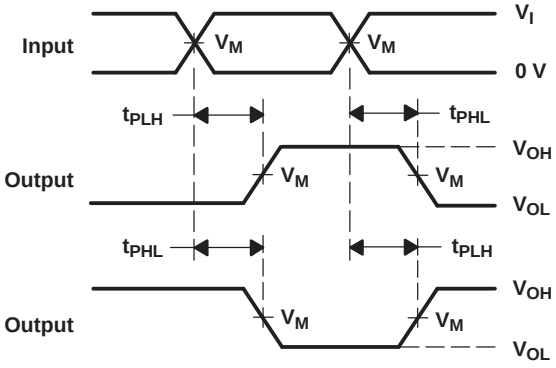
PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 10 MHz	0.8 V	4	pF
			1.2 ± 0.1 V	4	
			1.5 ± 0.1 V	4	
			1.8 V ± 0.15 V	4	
			2.5 V ± 0.2 V	4.2	
			3.3 V ± 0.3 V	4.4	

PARAMETER MEASUREMENT INFORMATION
(Propagation Delays, Setup and Hold Times, and Pulse Width)

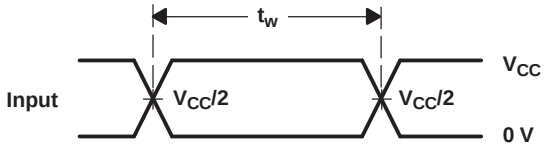


LOAD CIRCUIT

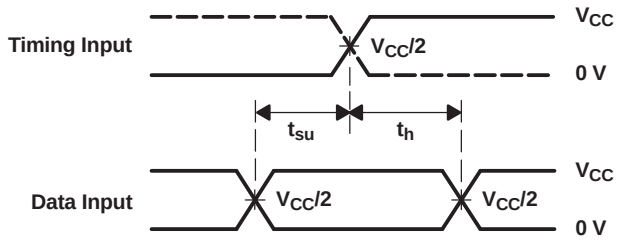
	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
PULSE DURATION

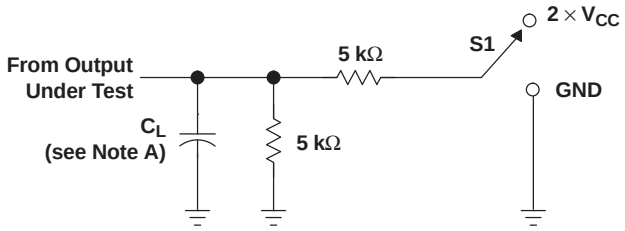


VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, for propagation delays t_r/t_f = 3 ns, for setup and hold times and pulse width t_r/t_f = 1.2 ns.
C. The outputs are measured one at a time, with one transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{pd}.
E. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

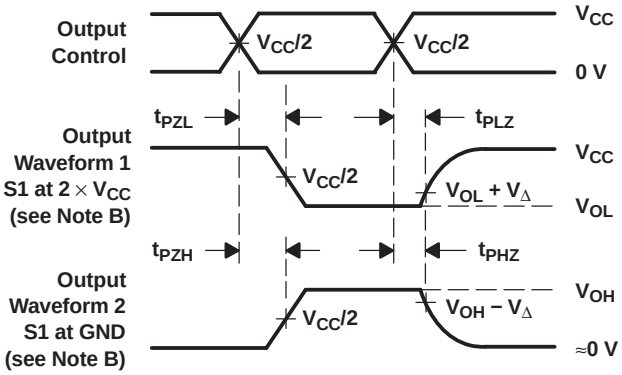
PARAMETER MEASUREMENT INFORMATION
(Enable and Disable Times)



LOAD CIRCUIT

TEST	S1
t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	$2 \times V_{CC}$ GND

	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_Δ	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f = 3 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUP1G17MDCKREP	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	BZU	Samples
V62/07623-01XE	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	BZU	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN74AUP1G17-EP :

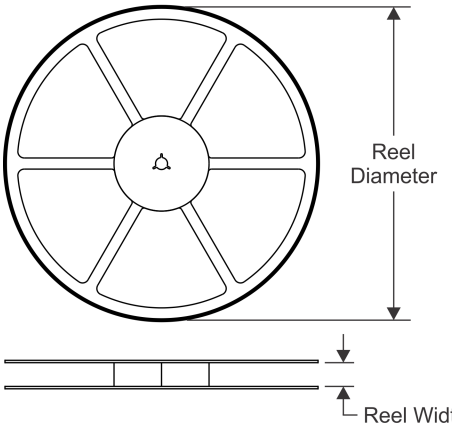
- Catalog: SN74AUP1G17

NOTE: Qualified Version Definitions:

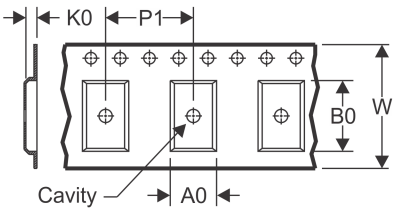
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

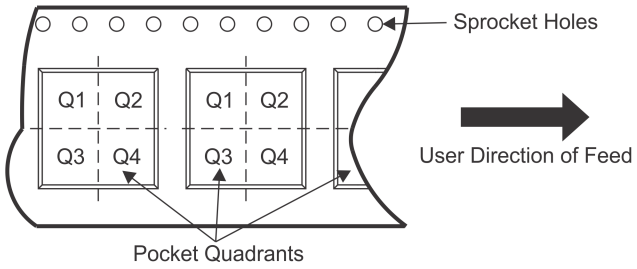


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

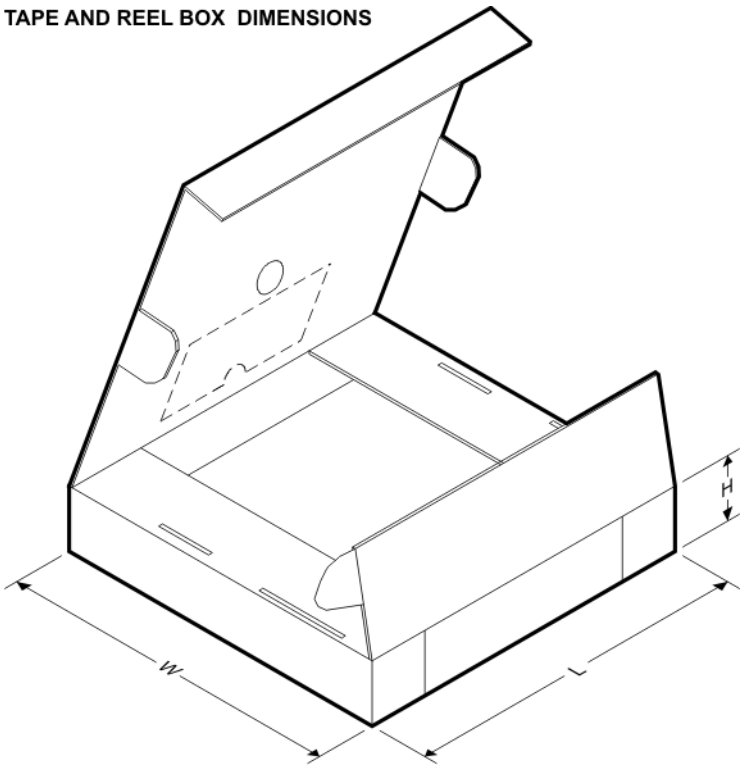
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1G17MDCKREP	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

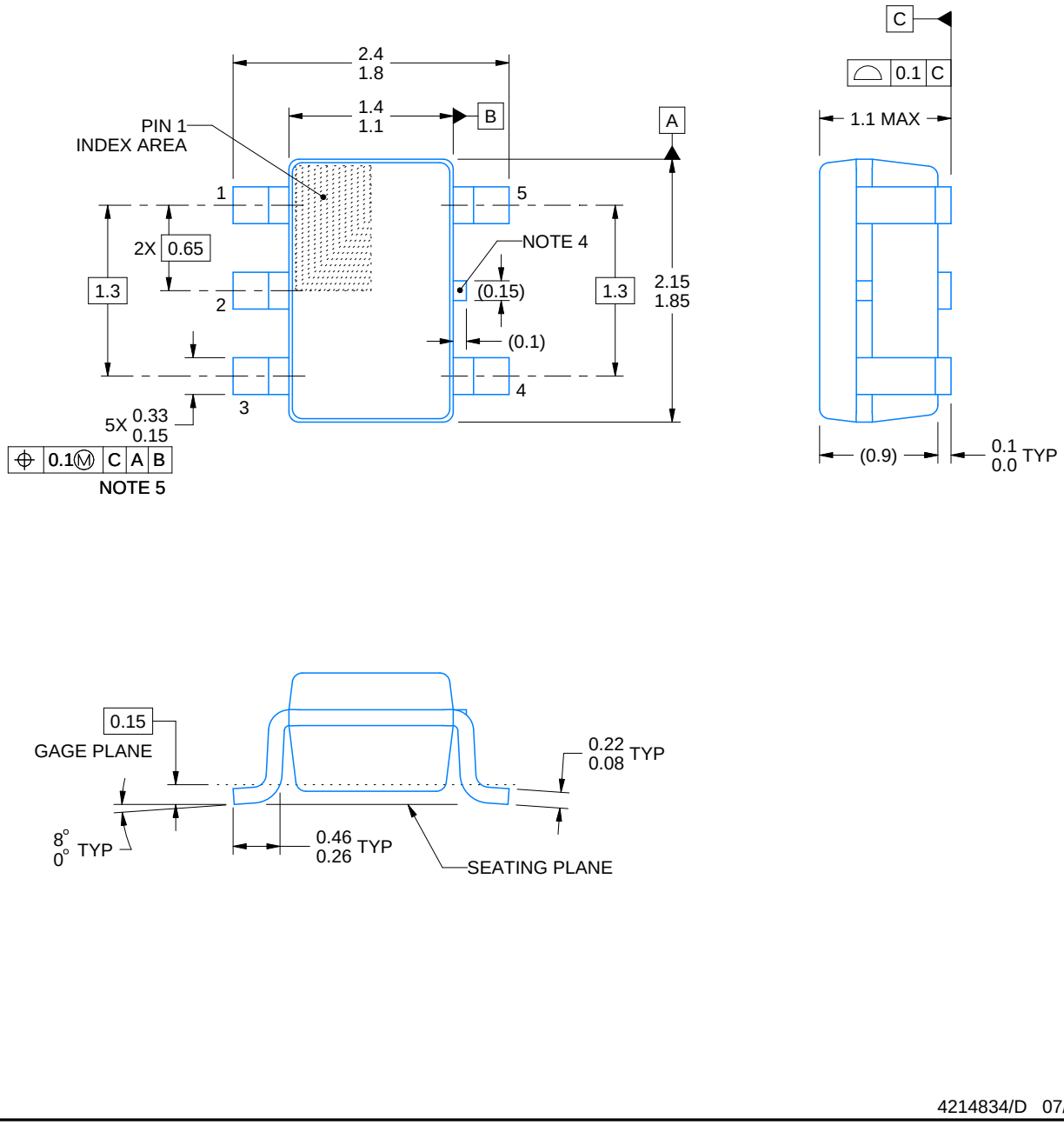
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP1G17MDCKREP	SC70	DCK	5	3000	202.0	201.0	28.0

PACKAGE OUTLINE

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



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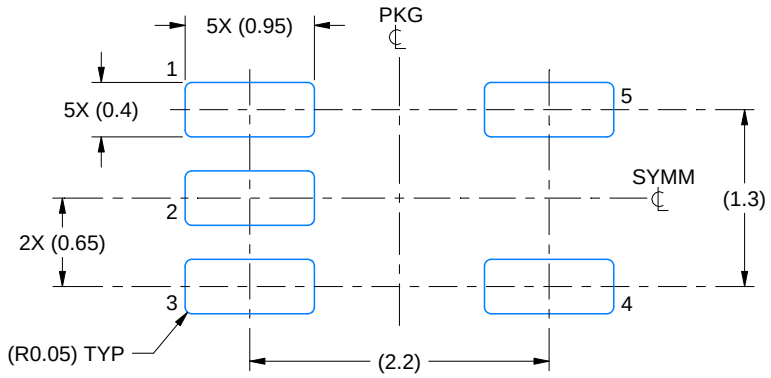
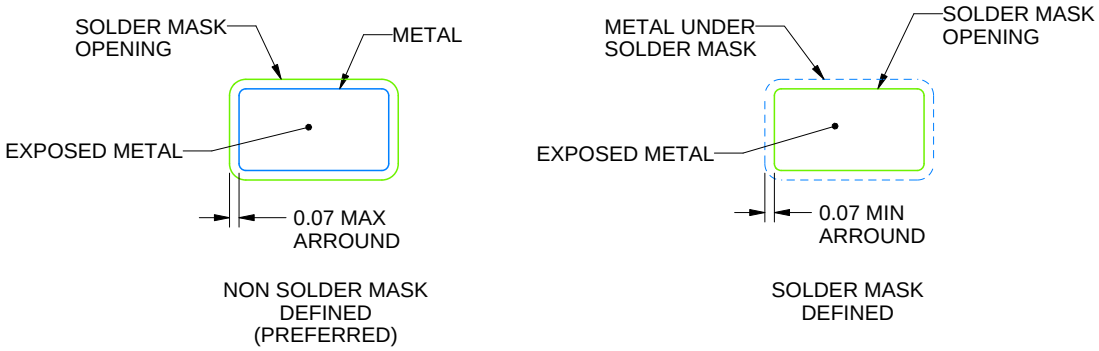
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

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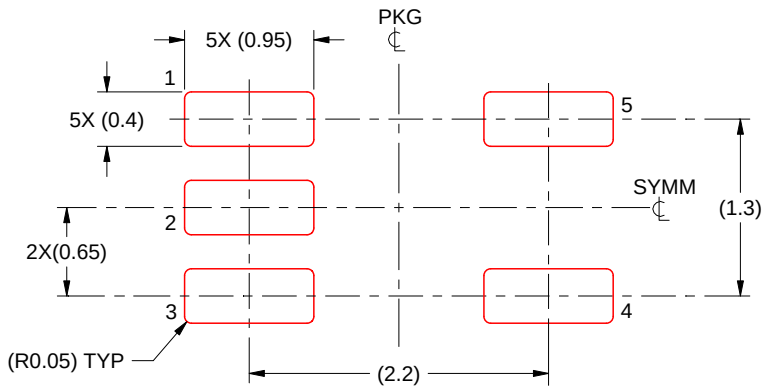
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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